



BSI Standards Publication

Mechanical standardization of semiconductor devices

Part 6-17: General rules for the preparation
of outline drawings of surface mounted
semiconductor device packages — Design
guide for stacked packages — Fine-pitch
ball grid array and fine-pitch land grid array
(P-PFBGA and P PFLGA)

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National foreword

This British Standard is the UK implementation of EN 60191-6-17:2011. It is identical to IEC 60191-6-17:2011.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Amendments issued since publication

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